



P-Channel Enhancement Mode Power MOSFET

Description

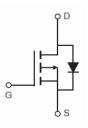
The RM60P04Y uses advanced trench technology and design to provide excellent $R_{\rm DS(ON)}$ with low gate charge .This device is well suited for use as a load switch or in PWM applications.

General Features

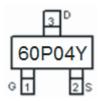
- V_{DS} =-60V,I_D =-4A
 - $R_{DS(ON)}$ <120m Ω @ V_{GS} =-10V
 - $R_{DS(ON)}$ <170m Ω @ V_{GS} =-4.5V
- High density cell design for ultra low Rdson
- Fully characterized avalanche voltage and current
- Excellent package for good heat dissipation

Application

- Load switch
- PWM application



Schematic diagram



Marking and pin Assignment



SOT-23-3L top view

Package Marking and Ordering Information

Device Marking	Device	Device Package	Reel Size	Tape width	Quantity
60P04Y	RM60P04Y	SOT-23-3L	Ø180mm	8 mm	3000 units

Absolute Maximum Ratings (T_c=25℃unless otherwise noted)

Parameter	Symbol	Limit	Unit
Drain-Source Voltage	VDS	-60	V
Gate-Source Voltage	V _G s	±20	V
Drain Current-Continuous	I _D	-4	А
Pulsed Drain Current	I _{DM}	-12	Α
Maximum Power Dissipation	P _D	1.5	W
Operating Junction and Storage Temperature Range	T _J ,T _{STG}	-55 To 150	°C

Thermal Characteristic

Thermal Resistance, Junction-to-Ambient(Note 2)	$R_{\theta JA}$	83.3	°C/W

Electrical Characteristics (T_C=25°C unless otherwise noted)

Parameter	Symbol	Condition	Min	Тур	Max	Unit	
Off Characteristics	<u>.</u>		•	•			
Drain-Source Breakdown Voltage	BV _{DSS}	V _{GS} =0V I _D =-250μA	-60	-	-	V	
Zero Gate Voltage Drain Current	I _{DSS}	V _{DS} =-60V,V _{GS} =0V	-	-	-1	μA	
Gate-Body Leakage Current	I _{GSS}	V _{GS} =±20V,V _{DS} =0V	-	-	±100	nA	
On Characteristics (Note 3)							
Gate Threshold Voltage	V _{GS(th)}	V _{DS} =V _{GS} ,I _D =-250μA	-1.5	-2.2	-3.0	V	
Drain-Source On-State Resistance	В	V_{GS} =-10V, I_D =-4A	-	106	120	mΩ	
Dialii-Source Off-State Resistance	R _{DS(ON)}	V _{GS} =-4.5V, I _D =-3A	-	135	170	mΩ	
Forward Transconductance	G FS	V _{DS} =-5V,I _D =-4A	-	10	-	S	
Dynamic Characteristics (Note4)	Dynamic Characteristics (Note4)						
Input Capacitance	C _{lss}	\/ - 20\/\/ -0\/	-	930	-	PF	
Output Capacitance	C _{oss}	V_{DS} =-30V, V_{GS} =0V, F=1.0MHz	-	85	-	PF	
Reverse Transfer Capacitance	C _{rss}	Γ-1.UIVIΠZ	-	35	-	PF	
Switching Characteristics (Note 4)	·						
Turn-on Delay Time	t _{d(on)}		-	8	-	nS	
Turn-on Rise Time	t _r	V_{DD} =-30V, R_L =7.5 Ω ,	-	4	-	nS	
Turn-Off Delay Time	t _{d(off)}	V_{GS} =-10 V , R_{G} =3 Ω	-	32	-	nS	
Turn-Off Fall Time	t _f		-	7	-	nS	
Total Gate Charge	Qg	V - 20 I - 4A	-	25	-	nC	
Gate-Source Charge	Q _{gs}	V_{DS} =-30, I_{D} =-4A, V_{GS} =-10V	-	3	-	nC	
Gate-Drain Charge	Q _{gd}	VGS10V	-	7	-	nC	
Drain-Source Diode Characteristics				•			
Diode Forward Voltage (Note 3)	V _{SD}	V _{GS} =0V,I _S =-4A	-		-1.2	V	
Diode Forward Current (Note 2)	Is		-	-	-4	Α	
Reverse Recovery Time	t _{rr}	T _J = 25°C, I _F =- 4A	-	25		nS	
Reverse Recovery Charge	Qrr	$di/dt = -100A/\mu s^{(Note3)}$	-	31		nC	

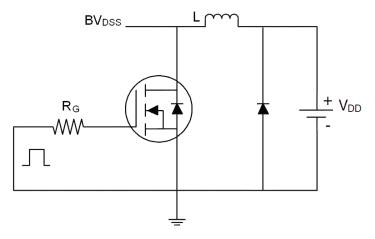
Notes:

- 1. Repetitive Rating: Pulse width limited by maximum junction temperature.
- **2.** Surface Mounted on FR4 Board, $t \le 10$ sec.
- 3. Pulse Test: Pulse Width \leq 300 μ s, Duty Cycle \leq 2%.
- 4. Guaranteed by design, not subject to production

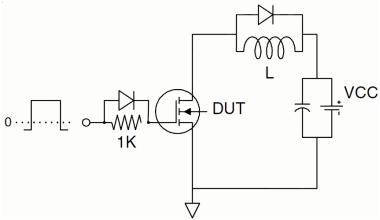


Test Circuit

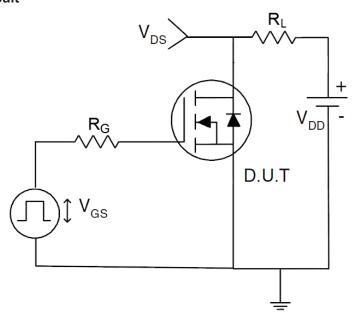
1) E_{AS} test Circuit



2) Gate charge test Circuit

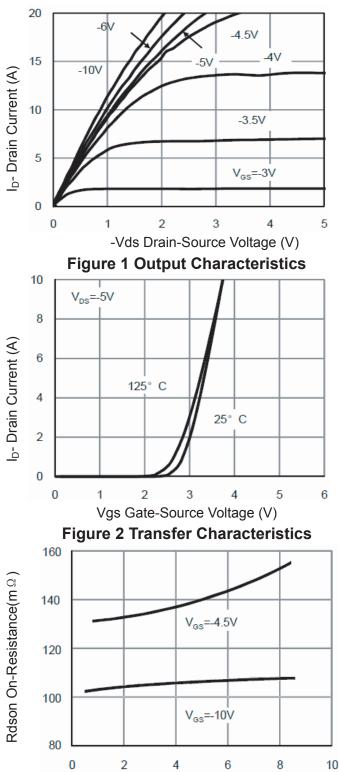


3) Switch Time Test Circuit





RATING AND CHARACTERISTICS CURVES (RM60P04Y)



- ID- Drain Current (A) Figure 3 Rdson- Drain Current

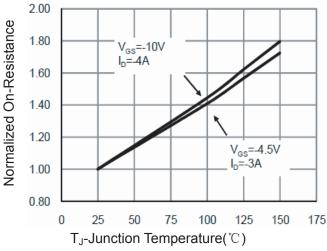
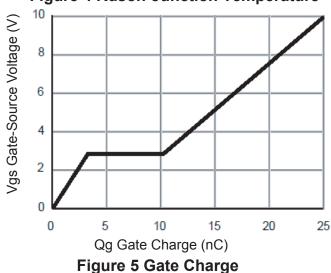


Figure 4 Rdson-Junction Temperature



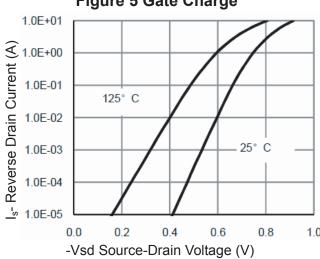


Figure 6 Source- Drain Diode Forward



RATING AND CHARACTERISTICS CURVES (RM60P04Y)

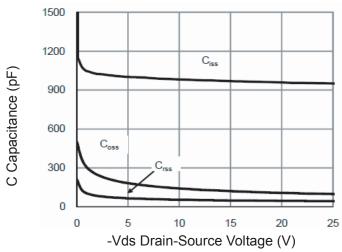


Figure 7 Capacitance vs Vds

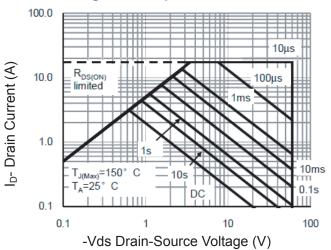
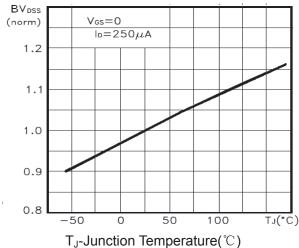
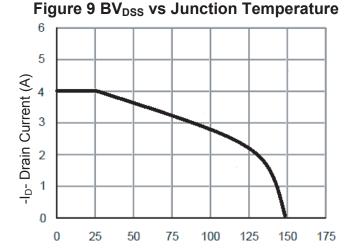
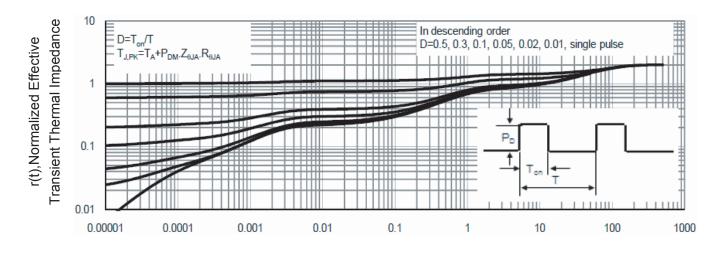


Figure 8 Safe Operation Area





T_J-Junction Temperature(°C) Figure 10 ID Current De-rating

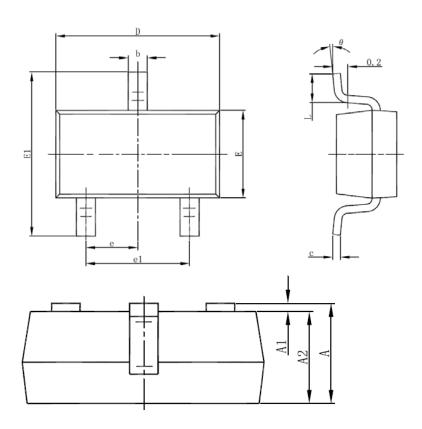


Square Wave Pluse Duration(sec)

Figure 11 Normalized Maximum Transient Thermal Impedance



SOT-23-3L Package Information



Symbol	Dimensions In Millimeters		Dimensions In Inches		
	Min	Max	Min	Max	
Α	1.050	1.250	0.041	0.049	
A1	0.000	0.100	0.000	0.004	
A2	1.050	1.150	0.041	0.045	
b	0.300	0.500	0.012	0.020	
С	0.100	0.200	0.004	0.008	
D	2.820	3.020	0.111	0.119	
E	1.500	1.700	0.059	0.067	
E1	2.650	2.950	0.104	0.116	
е	0.950(BSC)		0.037(BSC)		
e1	1.800	2.000	0.071	0.079	
L	0.300	0.600	0.012	0.024	
θ	0°	8°	0°	8°	

Notes

- 1. All dimensions are in millimeters.
- 2. Tolerance ±0.10mm (4 mil) unless otherwise specified
- 3. Package body sizes exclude mold flash and gate burrs. Mold flash at the non-lead sides should be less than 5 mils.
- 4. Dimension L is measured in gauge plane.
- 5. Controlling dimension is millimeter, converted inch dimensions are not necessarily exact.



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